

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7291803

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YEONHO KIM	03/31/2022
GEE YOUNG SHIN	03/31/2022
JAE YEON KIM	03/31/2022
JEAWAN KIM	03/31/2022
JUNG SAM GU	03/31/2022
JAE CHUN RYU	04/19/2022
SUNG-WOOK PARK	03/31/2022

RECEIVING PARTY DATA

Name:	HYUNDAI MOTOR COMPANY
Street Address:	12, HEOLLEUNG-RO, SEOCHO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Name:	KIA CORPORATION
Street Address:	12, HEOLLEUNG-RO, SEOCHO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Name:	HANON SYSTEMS
Street Address:	95, SINILSEO-RO, DAEDEOK-GU
City:	DAEJEON
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17725859

CORRESPONDENCE DATA

Fax Number: (202)739-3001

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2027393000

Email: wapatents@morganlewis.com, angie.ellis@morganlewis.com

Correspondent Name: MORGAN, LEWIS & BOCKIUS LLP
Address Line 1: 1111 PENNSYLVANIA AVENUE, NW
Address Line 4: WASHINGTON, D.C. 20004

ATTORNEY DOCKET NUMBER: 123223-5643-US

NAME OF SUBMITTER: ANGELA Y. ELLIS

SIGNATURE: /Angela Y. Ellis/

DATE SIGNED: 04/21/2022

Total Attachments: 8

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ASSIGNMENT-STATEMENT
Under 37 CFR 1.63 and 35 U.S.C. 115

TITLE OF THE INVENTION: MOUNTING STRUCTURE OF THERMAL MANAGEMENT MODULE FOR VEHICLE

As the below named inventor(s), I/We hereby declare that:

This Assignment-Statement is directed to:

- The application as filed, or
- United States Patent Application or PCT No. _____ filed on _____.

The above-identified application was made or authorized to be made by me/us.

I/We believe that I am/we are the original inventor(s) of a claimed invention in the application.

I/We hereby acknowledge that any willful false statement made in this Assignment-Statement is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, the undersigned,

1. **Yeonho KIM** of #B-301, 17, Ahasan-ro 78ga-gil, Gwangjin-gu, Seoul, Korea;
2. **Gee Young SHIN** of #1006-402, 45, Gwanggyohosugongwon-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea;
3. **Jae Yeon KIM** of #145-2604, 231, Dongtanbanseok-ro, Hwaseong-si, Gyeonggi-do, Korea;
4. **Jeawan KIM** of #202-1204, 11, Sicheong-ro 102beon-gil, Namyang-eup, Hwaseong-si, Gyeonggi-do, Korea;
5. **Jung Sam GU** of 95, Sinilseo-ro, Daedeok-gu, Daejeon, Korea;
6. **Jae Chun RYU** of 95, Sinilseo-ro, Daedeok-gu, Daejeon, Korea; and
7. **Sung-Wook PARK** of 95, Sinilseo-ro, Daedeok-gu, Daejeon, Korea

(hereinafter termed "Inventor"), respectively, have invented certain new and useful improvements in [MOUNTING STRUCTURE OF THERMAL MANAGEMENT MODULE FOR VEHICLE] and executed therefore an application for Letters Patent of the United States and

WHEREAS, **HYUNDAI MOTOR COMPANY**, a corporation of the State of Republic of Korea, having a place of business at 12, Heolleung-ro, Seocho-gu, Seoul, Republic of Korea; **Kia Corporation**, a corporation of the State of Republic of Korea, having a place of business at 12, Heolleung-ro, Seocho-gu,

Seoul, Republic of Korea; and **HANON SYSTEMS**, a corporation of the State of Republic of Korea, having a place of business at 95, Sinilseo-ro, Daedeok-gu, Daejeon, Korea (hereinafter termed "Assignee"), are desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventor (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventor to have been received in full from said Assignee:

1. Said Inventor do hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventor do hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventor shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor, their respective heirs, legal representatives and assigns.

4. Said Inventor do hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Inventor have executed and delivered this instrument to said Assignee as follows:

PATENT

Application No.
Attorney Docket No. 123223-5643-US

(1) Yeonho KIM

Date: 31. 3. 2022

Yeonho Kim

(2) Gee Young SHIN

Date: 31. 3. 2022

Gee Young Shin

(3) Jae Yeon KIM

Date: 31. 3. 2022

Jae Yeon Kim

(4) Jeawan KIM

Date: 31. 3. 2022

Jeawan kim

(5) Jung Sam GU

Date: 31. 3. 2022

Jung Sam Gu

PATENT

Application No.
Attorney Docket No. 123223-5643-US

(6) **Jae Chun RYU**

Date: _____

(7) **Sung-Wook PARK**

Date: 31. 3. 2022 Sung Wook PARK

ASSIGNMENT-STATEMENT
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As the below named inventor(s), I/We hereby declare that:

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- United States Patent Application or PCT No. _____ filed on _____.

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WHEREAS, the undersigned,

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5. **Jung Sam GU** of 95, Sinilseo-ro, Daedeok-gu, Daejeon, Korea;
6. **Jae Chun RYU** of 95, Sinilseo-ro, Daedeok-gu, Daejeon, Korea; and
7. **Sung-Wook PARK** of 95, Sinilseo-ro, Daedeok-gu, Daejeon, Korea

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Seoul, Republic of Korea; and **HANON SYSTEMS**, a corporation of the State of Republic of Korea, having a place of business at 95, Sinilseo-ro, Daedeok-gu, Daejeon, Korea (hereinafter termed "Assignee"), are desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventor (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventor to have been received in full from said Assignee:

1. Said Inventor do hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventor do hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventor shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventor in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor, their respective heirs, legal representatives and assigns.

4. Said Inventor do hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Inventor have executed and delivered this instrument to said Assignee as follows:

(1) **Yeonho KIM**

Date: _____

(2) **Gee Young SHIN**

Date: _____

(3) **Jae Yeon KIM**

Date: _____

(4) **Jeawan KIM**

Date: _____

(5) **Jung Sam GU**


Date: _____

PATENT

Application No.
Attorney Docket No. 123223-5643-US

(6) Jae Chun RYU

Date: 2022. 04. 19



(7) Sung-Wook PARK

Date: _____
